Attorney's Docket No.: Intel 10559-857001 / P17305

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Sarah E. Kim et al. Art Unit : 2814

Serial No.: 10/659,044 Examiner: Thao X. Le

Filed : September 9, 2003 Assignee : Intel Corporation

Title : THICK METAL LAYER INTEGRATED PROCESS FLOW TO IMPROVE

POWER DELIVERY AND MECHANICAL BUFFERING

## Mail Stop Amendment

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## RESPONSE TO RESTRICTION REQUIREMENT

Responsive to the action mailed October 15, 2004, applicant elects the invention of Group I drawn to the embodiment of a semiconductor device. The election is made with traverse.

Amendments to the claims begin on page 1 of this paper.

Remarks begin on page 7 of this paper.

## CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR \$1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Date of Deposit

Signature

November 15, 2004

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<u>Carroll Allman</u>
Typed or Printed Name of Person Signing Certificate